GLOSSARY OF TECHNICAL TERMS

"AGV"	automated guided vehicle
"AI/ML"	AI-powered machine learning
"AMR"	autonomous mobile robot
"AOI"	automated optical inspection
"APC"	advanced process control
"APIs"	application programming interface
"ASIC"	application-specific integrated circuit
"ATE"	standard semiconductor automated test equipment
"BOM"	bill of materials
"CAGR"	compound annual growth rate
"CAPA"	corrective and preventive action that is used to identify, investigate, and eliminate the root causes of product defects, non-conformities, and potential risks
"capex"	capital expenditure
"CPO"	co-packaged optics, an advanced integration method where SiPh devices and ASICs are combined onto a common platform within a single chip package
"CRM"	customer relationship management
"CTL"	chip testline
"datacom"	data communication
"DFMEA"	design failure mode and effect analysis, is a process used by engineers to identify and mitigate potential design flaws
"DOF"	degree-of-freedoms
"DTL"	die testline
"EDM"	enterprise digital manufacturing
"EICs"	electronic ICs
"EoL"	end of line
"ERP"	enterprise resource planning

"FAU"	fiber array unit
"FDC"	fault detection and classification system
"G" or "Gb"	gigabit, a unit of digital information equal to 1 billion bits
"GEM"	generic equipment model. It enables automated manufacturing equipment to exchange data with factory host systems for remote monitoring and control
"GPU"	graphics processing unit
"HJT"	heterojunction technology
"ICs"	integrated circuits
"IDMs"	integrated device manufacturers
"LPCVD"	low-pressure chemical vapor deposition process that uses heat to initiate a reaction of a precursor gas on the solid substrate
"MEMS"	micro-electromechanical systems
"MES"	manufacturing execution system
"MT"	mechanical transfer
"MTL"	module testline
"nm"	nanometer, a unit of length
"OCS"	optical circuit switching
"OEE"	overall equipment effectiveness
"OEs"	optical engines
"optical I/O"	optical input/output
"OSATs"	outsourced semiconductor assembly and test
"PCM"	process control master
"PECVD"	plasma-enhanced chemical vapor deposition, a specialized technology that utilizes plasma to enable deposition at lower temperatures
"PE-POLY"	plasma-enhanced polysilicon deposition
"PICs"	photonic integrated circuits

"PLM"	product lifecycle management
"PWB"	proprietary photonic wire bond
"PV"	photovoltaics, the conversion of light into electricity using semiconducting materials that exhibit the photovoltaic effect
"SDKs"	software development kits
"SECS"	equipment interface protocol for equipment-to-host data communications
"SiPh"	silicon photonics
"SPC"	statistical process control
"T" or "Tb"	terabit, a unit of digital information equal to one trillion bits
"telecom"	telecommunication
"TOPCon"	tunnel oxide passivated contact, an advanced technology for PV cells that uses an ultra-thin silicon oxide layer between a heavily doped polycrystalline silicon layer and the silicon wafer to improve performance
"µm"	micrometers
"WIP"	work-in-process
"WTL"	wafer testline
"XBC"	extended back-contact, a high-efficiency PV cell technology where all electrical contacts are moved to the rear of the cell